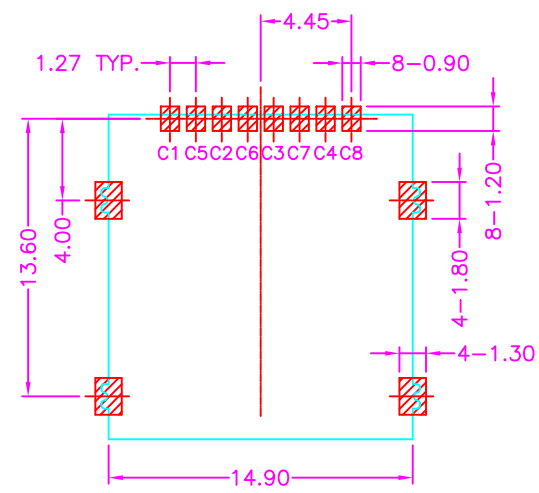
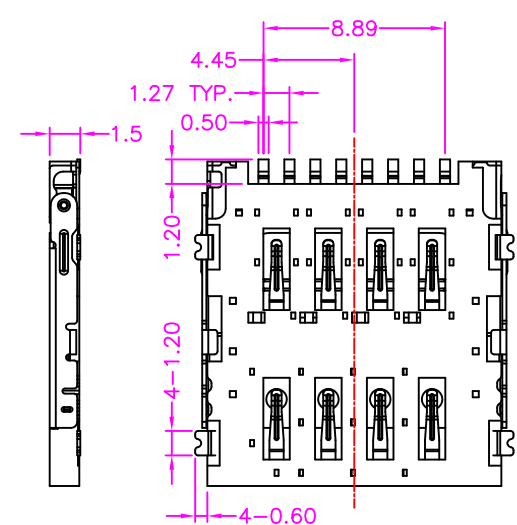
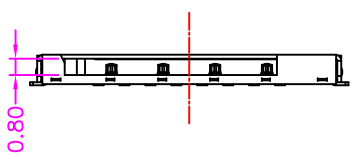


SECTION A-A



P.C.B. LAYOUT
TOP VIEW ±0.05

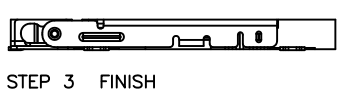
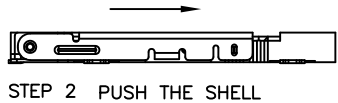
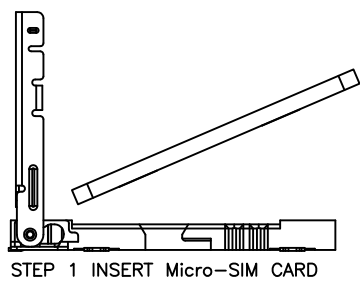
KEEP AREA
PAD AREA

MATERIALS

HOUSING: HI-TEMP. PLASTIC (UL 94V-0),
SHELL: SUS, NICKEL PLATING
SOLDER PAD: SUS, GOLD FLASH
TERMINAL: COPPER ALLOY, GOLD PLATED

SPECIFICATION

CURRENT RATING: 0.5 AMP MAX
DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
CONTACT RESISTANCE: 100m OHMS MAX
INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
OPERATION TEMPERATURE: -25°C~+85°C



PART NUMBER:

4MCQF - 0 8 * - 1 2 1

SERIES
NO. OF POS.
TAPE REEL PACKAGE

CONTACT PLATED OPTION

- 1: GOLD FLASH
- 3: 3u" GOLD
- 5: 5u" GOLD
- 6: 10u" GOLD
- 7: 15u" GOLD
- 9: 30u" GOLD

SIM CARD		Cyberconn Technology Co., Ltd. www.cyberconn.com.tw Tel:+886-3-4951314						
Pin No.	NAME	TOLERANCES		TITLE				
C1	VCC	X.X ±0.3	MEMORY CARD SERIES MICRO SIM CARD, 8 PIN, PCB MOUNT, SMT METAL SHIELD FEMALE, HINGE TYPE					
C2	RST	X.XX ±0.2						
C3	CLK	X.XXX ±0.1						
C4	RESERVED	Angle ±5°						
C5	GND							
C6	VPP			DRAWN BY	CHECKED BY	APPROVED BY		
C7	I/O			<i>Tina</i>	<i>Lion</i>	<i>Benson</i>		
C8	RESERVED	10140	UNIT	SCALE	SIZE	DRAW NO.	REV.	Sheet
			MM	NONE	A4	4MCQF-001	A	1/1

A	RELEASE	2014.12.11
REV.	DESCRIPTION	DATE